#14/Amdt C



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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| Applicant: | Heinen | Art Unit: | 2823 |
| Serial No.: | 09/186,973 | Examiner: | Shukla, R. |
| Filed: | 11/05/98 | Docket: | TI-23158 |
| For: | **WAFER-SCALE ASSEMBLY OF CHIP-SIZE PACKAGES** | | |

**AMENDMENT 37 CFR 1.115**

November 5, 2001

Assistant Commissioner
for Patents
Washington, D.C. 20231

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Emily C. Chantry 11/5/01
Date

Sir:

Responsive to the Office Action of July 5, 2001, please amend the application as follows:

In the Claims:

14. (Amended) A method for the fabrication of a semiconductor assembly:

providing a semiconductor wafer [having] comprising a plurality of undivided integrated circuit[s] chips, each circuit chip having a plurality of metal contact pads as electrical entry and exit ports;

forming a planar array of solder balls attached to said contact pads of said plurality of chips on said semiconductor wafer so that each of said contact pads is contacted by one of said solder balls;

providing an interposer of electrically insulating material having first and second opposite surfaces and electrically conductive paths from said first [one] surface to [the opposite] said second surface, forming electrical entry and exit ports on said insulating interposer;

aligning said interposer with said solder balls so that each port is placed into